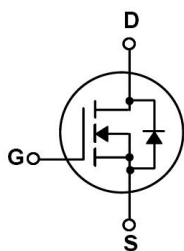


**/ Descriptions****/ Features****/ Applications****/ Equivalent Circuit****/ Pinning****/  $h_{FE}$  Classifications & Marking**

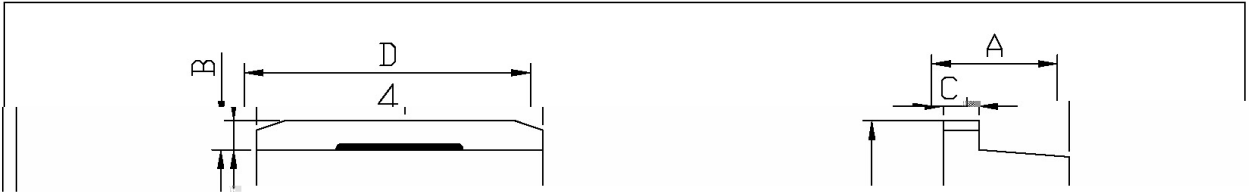
BRB840

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BRB840



/ Package Dimensions

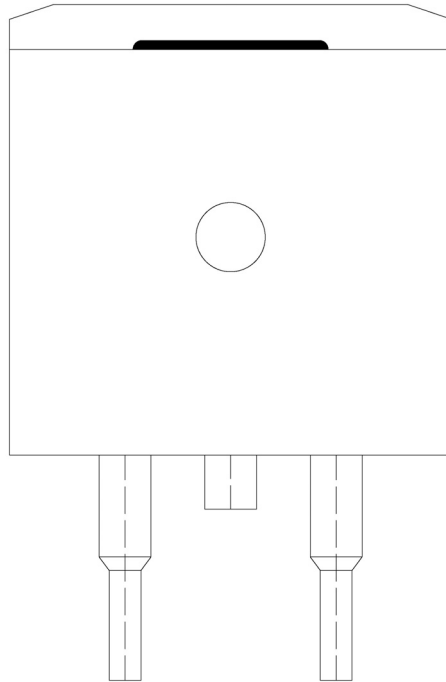


单位: mm

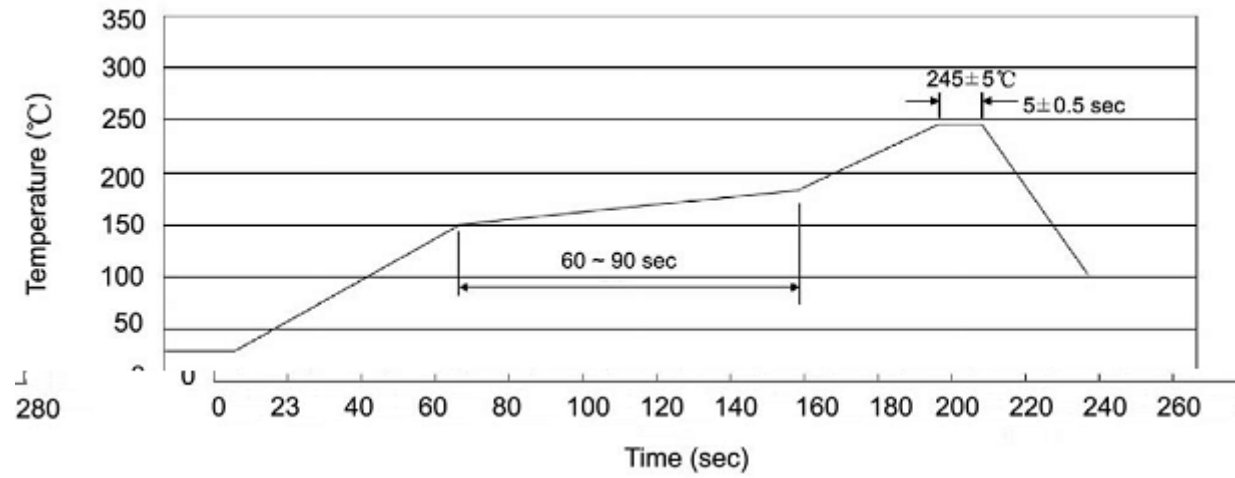
| Dimensions in Millimeters |      |       | Dimensions in Millimeters |       |       |
|---------------------------|------|-------|---------------------------|-------|-------|
| Symbol                    | Min  | Max   | Symbol                    | Min   | Max   |
| A                         | 4.30 | 4.70  | E                         | 9.00  | 9.40  |
| B                         | 1.00 | 1.40  | e1                        | 2.34  | 2.74  |
| b                         | 0.70 | 0.90  | e2                        | 4.88  | 5.28  |
| b1                        | 1.15 | 1.35  | L1                        | 15.00 | 16.00 |
| b2                        | 0.40 | 0.60  | L2                        | 2.24  | 2.74  |
| C                         | 1.20 | 1.40  | L3                        | 1.20  | 1.60  |
| D                         | 9.80 | 10.20 |                           |       |       |

T.P-263

/ Marking Instructions



(     ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

℃

/ Packaging SPEC.

| 封装形式 | 包装数量 |      |     |     |     | 包装尺寸 |   |   |
|------|------|------|-----|-----|-----|------|---|---|
|      | 只 卷盘 | 卷盘 盒 | 只 盒 | 盒 箱 | 只 箱 |      | 盒 | 箱 |
|      |      |      |     |     |     |      |   |   |